ECSE 524. INTERCONNECTS AND SIGNAL INTEGRITY.

Credits: 3

Offered by: Electrical & Computer Engr (Faculty of Engineering)

This course is not offered this catalogue year.

Description

Interconnect structures, signal integrity issues: reflection, crosstalk, noise, electromagnetic interference, Lossy transmission lines, RLGC matrix representations, wave propagation in multilayered substrates, periodically loaded lines, Floquet's theorem, power distribution network, simultaneous switching noise, packaging structures, chip interconnection technologies, substrate integrated waveguides, methods for experimental characterization of interconnects, signal integrity CAD tools.

- (3-0-6)
- Prerequisites: (ECSE 334 or ECSE 335) and (ECSE 352 or ECSE 353 or ECSE 354)